

TLP5214

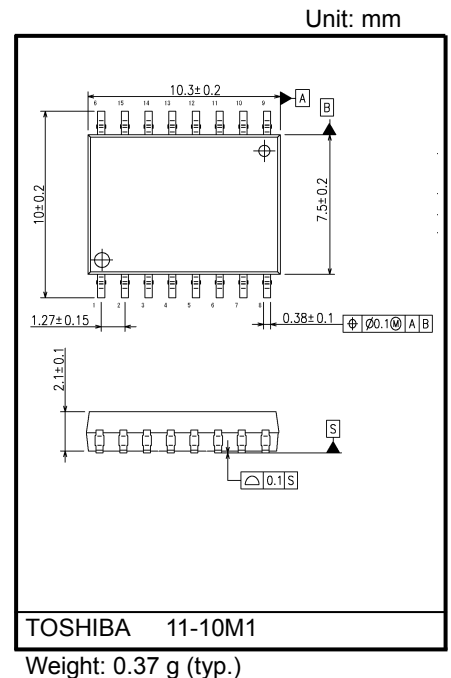
Isolated IGBT/Power MOSFET gate drive
 AC and brushless DC motor drives
 Industrial Inverters and Uninterruptible Power Supply (UPS)

The TLP5214 is a highly integrated 4.0A output current IGBT gate drive photocoupler housed in a long creepage and clearance SO16L package.
 The TLP5214, a smart gate driver photocoupler, includes functions of IGBT desaturation detection, isolated fault status feedback, soft IGBT turn-off, active Miller clamping and under voltage lockout (UVLO).
 This photocoupler is suitable for driving IGBT and power MOSFET used in inverter applications.
 The TLP5214 consists two GaAs infrared light-emitting diodes (LEDs) and two high-gain and high-speed ICs. They realize high current, high-speed output control and output fault status feedback.

- Peak output current: ± 4.0 A (max)
- Guaranteed performance over temperature: -40 to 110°C
- Supply current: 3.5 mA (max)
- Power supply voltage: 15 to 30 V
- Threshold input current: $I_{FLH} = 6$ mA (max)
- Switching time (t_{pLH} / t_{pHL}): 150 ns (max)
- Common mode transient immunity: ± 35 kV/ μs (min)
- Isolation voltage: 5000 Vrms (min)

• Construction mechanical rating

	SO16L
Height	2.3 mm (max)
Creepage Distance	8.0 mm (min)
Clearance	8.0 mm (min)
Insulation Thickness	0.4 mm (min)

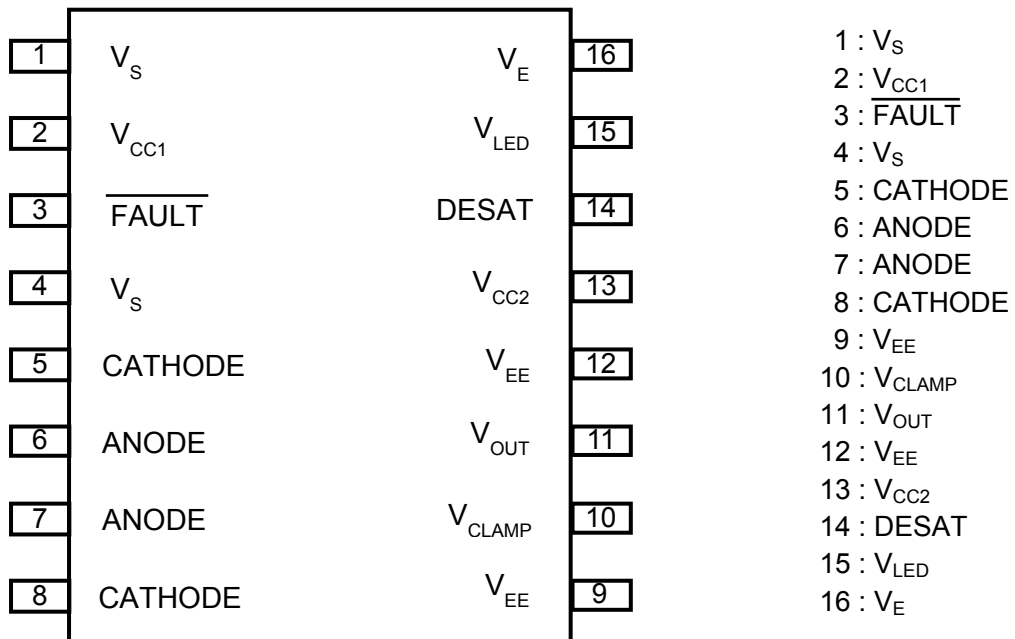


Truth Table

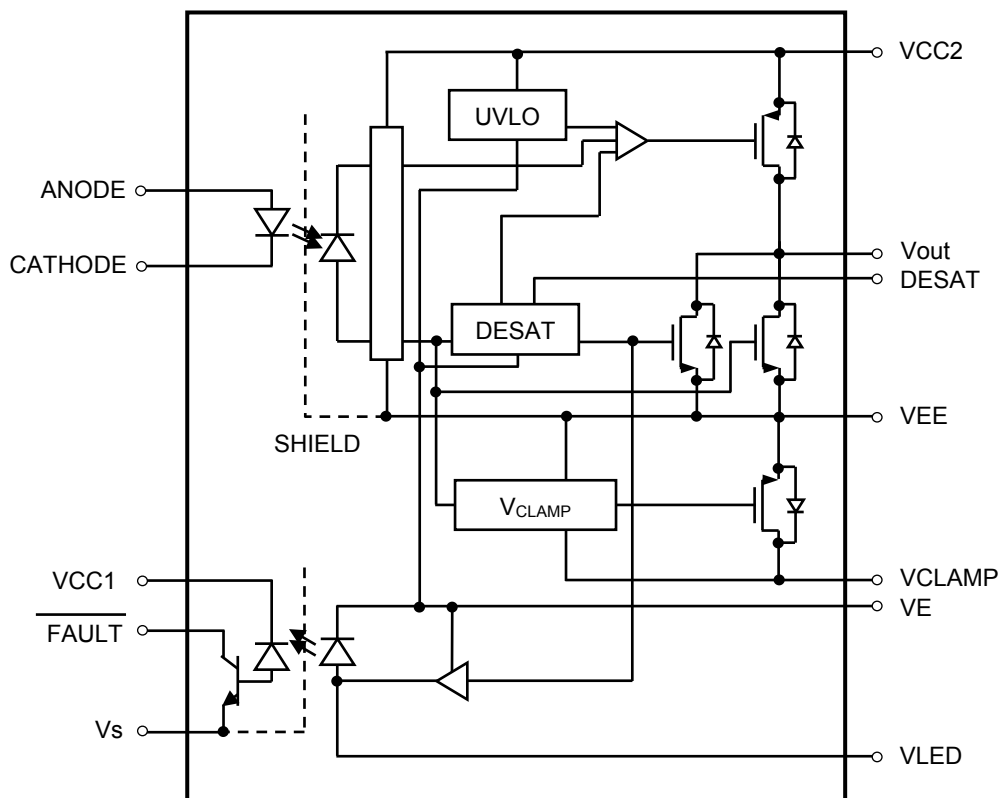
I_F	UVLO ($V_{CC2}-V_E$)	DESAT (14Pin DESAT Terminal Input)	FAULT (3Pin FAULT Terminal Output)	V_o
OFF	Not Active ($> V_{UVLO}^+$)	Not Active	High	Low
ON	Not Active ($> V_{UVLO}^+$)	Low ($< V_{DESATth}$)	High	High
ON	Not Active ($> V_{UVLO}^+$)	High ($> V_{DESATth}$)	Low (FAULT)	Low
ON	Active ($< V_{UVLO}^-$)	Not Active	High	Low
OFF	Active ($< V_{UVLO}^-$)	Not Active	High	Low

Start of commercial production
 2014-05

Pin Configuration



Internal Circuit



Note : A 1- μ F bypass capacitor must be connected between pins 9 and 13, pins 13 and 16.

Absolute Maximum Ratings (Note) (Ta = 25°C ,Unless otherwise specified)

	Characteristics	Symbol	Rating	Unit	
LED	Input forward current	I_F	25	mA	
	Input forward current derating (Ta ≥ 95°C)	$\Delta I_F / \Delta T_a$	-1	mA/°C	
	Peak transient input forward current (Note 1)	I_{FPT}	1	A	
	Peak transient input forward current derating (Ta ≥ 95°C)	$\Delta I_{FPT} / \Delta T_a$	-25	mA/°C	
	Reverse Input Voltage	V_R	6	V	
	Input power dissipation	P_D	40	mW	
	Input power dissipation derating (Ta ≥ 95°C)	$\Delta P_D / \Delta T_a$	-1.3	mW/°C	
Detector	Positive Input Supply Voltage	V_{CC1}	-0.5 to 7	V	
	"H" peak output current	Ta = -40 to 110 °C (Note 2)	I_{OPH}	-4.0	A
	"L" peak output current		I_{OPL}	+4.0	A
	FAULT Output Current	I_{FAULT}	8	mA	
	FAULT Pin Voltage	V_{FAULT}	-0.5 to V_{CC1}	V	
	Total Output Supply Voltage	$(V_{CC2} - V_{EE})$	-0.5 to 35	V	
	Negative Output Supply Voltage	$(V_E - V_{EE})$	-0.5 to 15	V	
	Positive Output Supply Voltage	$(V_{CC2} - V_E)$	-0.5 to 35 - $(V_E - V_{EE})$	V	
	Output voltage	V_O	-0.5 to V_{CC2}	V	
	Peak Clamping Sinking Current	I_{Clamp}	1.7	A	
	Miller Clamping Pin Voltage	V_{Clamp}	-0.5 to V_{CC2}	V	
	DESAT Voltage	V_{DESAT}	V_E to $V_E + 10$	V	
	Output power dissipation	P_O	160	mW	
	Output power dissipation (Ta ≥ 95°C)	$\Delta P_O / \Delta T_a$	-5.3	mW/°C	
	Common	Operating temperature range	T_{opr}	-40 to 110	°C
Storage temperature range		T_{stg}	-55 to 125	°C	
Lead soldering temperature (10 s) (Note 3)		T_{sol}	260	°C	
Isolation voltage (AC, 1 minute, R.H. ≤ 60%) (Note 4)		BV_S	5000	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note: A ceramic capacitor (1 μF) should be connected from pin 9 to pin 13 and from pin 13 to pin 16 to stabilize the operation of the high gain linear amplifier. Furthermore, in case $V_E - V_{EE} > 0V$, a bypass capacitor, which has good high frequency characteristic, a ceramic capacitor (1 μF) should be connected from pin 9 to pin 16. Failure to provide the bypassing may impair the switching property. The total lead length between capacitor and coupler should not exceed 1 cm.

Note 1: Pulse width $P_W \leq 1 \mu s$, 300 pps

Note 2: Exponential waveform pulse width $P_W \leq 0.2 \mu s$, $f \leq 15 \text{ kHz}$, $V_{CC} = 15 \text{ V}$

Note 3: For the effective lead soldering area.

Note 4: This device considered a two-terminal device: pins 1, 2, 3, 4, 5, 6, 7 and 8 are shorted together, and pins 9, 10, 11, 12, 13, 14, 15 and 16 are shorted together.

Recommended Operating Conditions

Characteristics	Symbol	Min	Typ.	Max	Unit
Total Output Supply Voltage (Note 5)	$(V_{CC2}-V_{EE})$	15	—	30	V
Negative Output Supply Voltage	(V_E-V_{EE})	0	—	15	V
Positive Output Supply Voltage	$(V_{CC2}-V_E)$	15	—	$30 - (V_E-V_{EE})$	V
Input On-State Current (Note 6)	$I_{F(ON)}$	7.5	—	12	mA
Input On-State Voltage	$V_{F(OFF)}$	0	—	0.8	V
Operating frequency (Note 7)	f	—	—	50	kHz

Note : Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Note 5 : If the V_{CC} rise slope is sharp, an internal circuit might not operate with stability. Please design the V_{CC} rise slope under $3.0 \text{ V} / \mu\text{s}$.

Note 6 : Input signal rise time (fall time) $\leq 0.5 \mu\text{s}$.

Note 7 : Exponential waveform. $I_{OPH} \geq -4.0 \text{ A} (\leq 90 \text{ ns})$, $I_{OPL} \leq 4.0 \text{ A} (\leq 90 \text{ ns})$, $T_a = 110^\circ\text{C}$

Electrical Characteristics ($T_a = -40$ to 110°C , unless otherwise specified)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.*	Max	Unit
Input Forward Voltage	V_F	—	$I_F = 10\text{mA}$, $T_a = 25^\circ\text{C}$	1.4	—	1.8	V
Input Reverse Current	I_R	—	$V_R = 5\text{V}$	—	—	10	μA
Input Capacitance	C_i	—	$V=0$, $f=1\text{MHz}$, $T_a = 25^\circ\text{C}$	—	95	—	pF
FAULT Low Level Output Voltage	$V_{\overline{\text{FAULTL}}}$	—	$I_{\overline{\text{FAULT}}} = 1.1 \text{ mA}$, $V_{CC1}=5.5\text{V}$	—	0.2	0.4	V
			$I_{\overline{\text{FAULT}}} = 1.1 \text{ mA}$, $V_{CC1}=3.3\text{V}$	—	0.2	0.4	
FAULT High Level Output Current	$I_{\overline{\text{FAULTH}}}$	—	$V_{\overline{\text{FAULT}}} = 5.5\text{V}$, $V_{CC1} = 5.5 \text{ V}$, $T_a = 25^\circ\text{C}$	—	—	0.5	μA
			$V_{\overline{\text{FAULT}}} = 5.5 \text{ V}$, $V_{CC1} = 3.3 \text{ V}$, $T_a = 25^\circ\text{C}$	—	—	0.3	
High Level Output Current (Note 8)	I_{OPH}	1	$V_O = V_{CC2} - 4 \text{ V}$	—	-4.0	-1.2	A
			$V_O = V_{CC2} - 7 \text{ V}$	—	-6.5	-3.0	
Low Level Output Current (Note 8)	I_{OPL}	2	$V_O = V_{EE} + 2.5 \text{ V}$	1.2	3.5	—	A
			$V_O = V_{EE} + 7 \text{ V}$	3	5.5	—	
Low Level Output Current During Fault Condition	I_{OLF}	—	$V_O - V_{EE} = 14 \text{ V}$	90	150	230	mA
High Level Output Voltage	V_{OH}	3	$I_O = -100 \text{ mA}$	$V_{CC2}-0.3$	$V_{CC2}-0.2$	—	V
Low Level Output Voltage	V_{OL}	5	$I_O = 100 \text{ mA}$	—	0.1	0.2	
Clamp Pin Threshold Voltage	V_{iClamp}	—	—	—	3.0	—	
Clamp Low Level Sinking Current	I_{CL}	—	$V_O = V_{EE} + 2.5\text{V}$	0.56	1.8	—	A
High Level Supply Current	I_{CC2H}	5	$I_O = 0 \text{ mA}$	—	2.4	3.5	mA
Low Level Supply Current	I_{CC2L}	6	$I_O = 0 \text{ mA}$	—	2.3	3.5	
Blanking Capacitor Charging Current	I_{CHG}	7	$V_{DESAT} = 2\text{V}$	-0.13	-0.24	-0.33	
Blanking Capacitor Discharge Current	I_{DSCHG}	8	$V_{DESAT} = 7\text{V}$	10	49	—	V
DESAT Threshold Voltage	V_{DESAT}	—	$V_{CC2}-V_E > V_{UVLO-}$	6	6.5	7.5	
UVLO Threshold Voltage	V_{UVLO+}	9	$V_O > 5\text{V}$	10.5	11.6	13.5	
	V_{UVLO-}	10	$V_O < 5\text{V}$	9.2	10.3	11.1	
UVLO hysteresis	$UVLO_{HYS}$	—	—	—	1.3	—	

(*): All typical values are at $T_a = 25^\circ\text{C}$

Note 8: I_O application time $\leq 50 \mu\text{s}$, 1 pulse

Electrical Characteristics (Ta = -40 to 110 °C, unless otherwise specified)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.*	Max	Unit
Threshold Input Current(L/H)	I _{FLH}	10	V _{CC} = 30 V, V _O < 5 V	—	0.8	6	mA
Threshold Input Voltage (H/L)	V _{FHL}	—	V _{CC} = 30 V, V _O > 5 V	0.8	—	—	V

(*): All typical values are at Ta = 25°C

Note : This product is more sensitive than conventional products to electrostatic discharge (ESD) owing to its low power consumption design.

It is therefore all the more necessary to observe general precautions regarding ESD when handling this component.

Isolation Characteristics(NOTE) (Ta = 25 °C)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Capacitance input to output	C _S	V _S = 0 V, f = 1 MHz	—	1.0	—	pF
Isolation resistance	R _S	R.H. ≤ 60 %, V _S = 500 V	1×10 ⁻¹²	1×10 ⁻¹⁴	—	Ω
Isolation voltage	BV _S	AC, 1 minute	5000	—	—	V _{rms}
		AC, 1 second, in oil	—	10000	—	
		DC, 1 minute, in oil	—	10000	—	V _{dc}

Note: This device considered a two-terminal device: pins 1, 2, 3, 4, 5, 6, 7 and 8 are shorted together, and pins 9, 10, 11, 12, 13, 14, 15 and 16 are shorted together.

Switching Characteristics (Ta = -40 to 110 °C, unless otherwise specified)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.*	Max	Unit	
Propagation delay time (Note 9)	L → H	t _{pLH}	V _{CC2} = 30 V R _g = 10 Ω C _g = 25 nF Duty = 50%	I _F = 0 → 10 mA	50	85	150	ns
	H → L	t _{pHL}		I _F = 10 → 0 mA	50	90	150	
Output rise time (10–90 %) (Note 9)	t _r			I _F = 0 → 10 mA	—	32	—	
Output fall time (90–10 %) (Note 9)	t _f			I _F = 10 → 0 mA	—	18	—	
Pulse with distortion (Note 9)	t _{pHL} - t _{pLH}			I _F = 0 ↔ 10 mA	—	—	50	
Propagation delay skew (device to device) (Note 9)(Note 10)	t _{psk}			I _F = 0 ↔ 10 mA	-80	—	80	
DESAT Sense to 90% Delay	t _{DESAT(90%)}	12		C _{DESAT} = 100pF, R _g = 10 Ω	—	180	500	
DESAT Sense to 10% Delay	t _{DESAT(10%)}		C _g = 25nF, V _{CC2} = 30 V R _F = 2.1kΩ	—	3.5	5		
DESAT Sense to Low Level FAULT Signal Delay	t _{DESAT(FAULT)}		C _{DESAT} = 100pF, R _g = 10 Ω	—	300	500	ns	
DESAT Sense to Low Propagation Delay	t _{DESAT(LOW)}		C _g = 25nF, V _{CC2} = 30 V R _F = 2.1kΩ	—	200	—		
DESAT Input Mute	t _{DESAT(MUTE)}		C _F = Open	7	14	—	μs	
RESET to High Level FAULT Signal Delay	t _{RESET(FAULT)}		V _{CC1} = 5.5V	0.2	0.45	2		
Common Mode Transient Immunity at High Level Output	CM _H		13	I _F = 10 mA V _{O (min)} = 26 V	±35	—	—	kV/μs
Common Mode Transient Immunity at Low Level Output	CM _L	I _F = 0 mA V _{O (max)} = 1 V		±35	—	—		

(*): All typical values are at Ta = 25 °C.

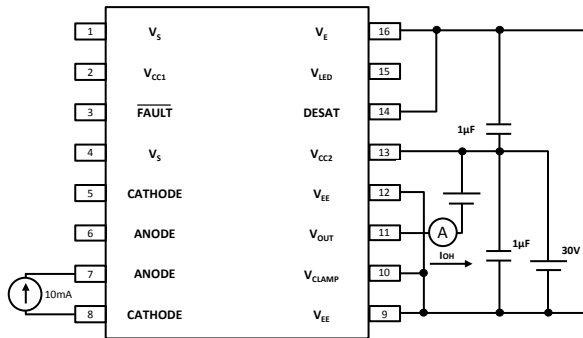
Note 9: Input signal (f = 10 kHz, duty = 50%, tr = tf = 5 ns or less)

CL is approximately 15 pF which includes probe and stray wiring capacitance.

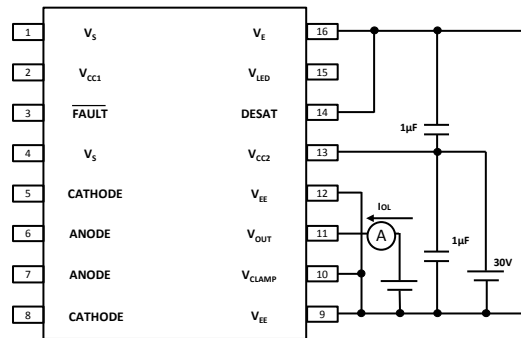
Note 10: The propagation delay skew, t_{psk}, is equal to the magnitude of the worst-case difference in t_{pHL} and/or t_{pLH} that will be seen between units at the same given conditions (supply voltage, input current, temperature, etc).

Test Circuit

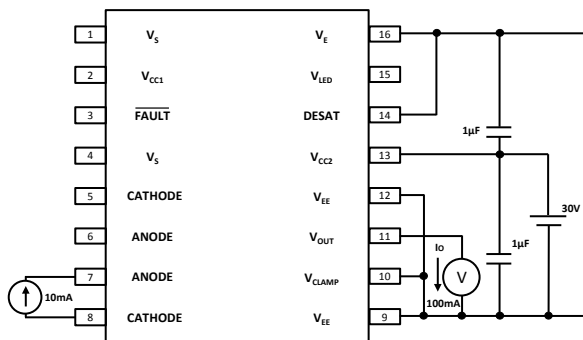
Test Circuit 1: I_{OPH}



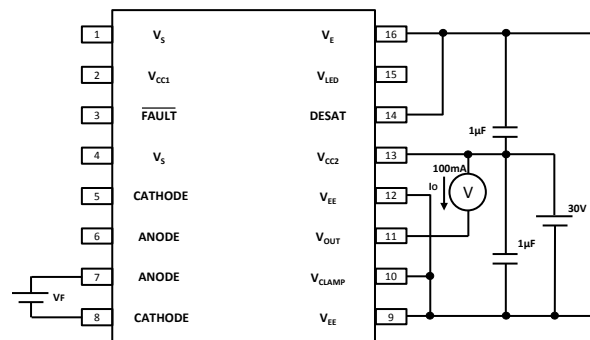
Test Circuit 2: I_{OPL}



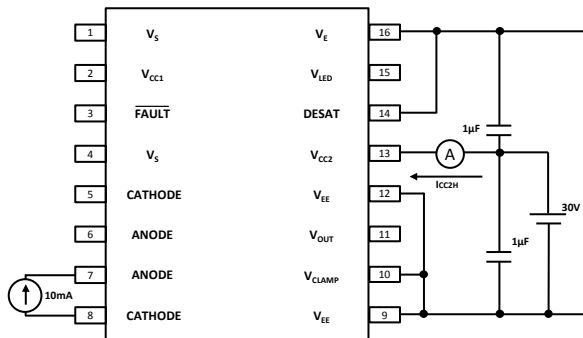
Test Circuit 3: V_{OH}



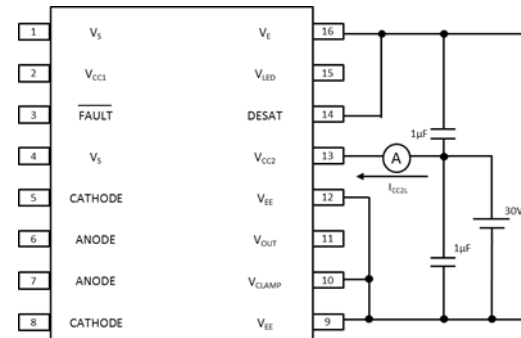
Test Circuit 4: V_{OL}



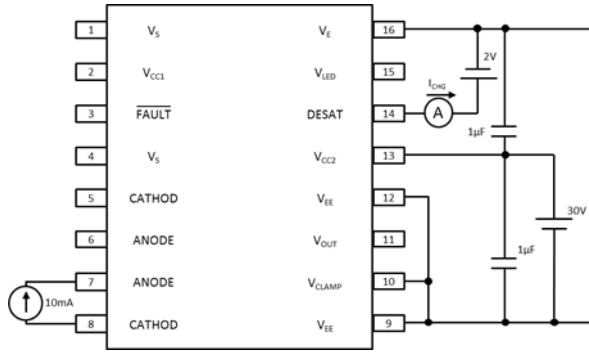
Test Circuit 5: I_{CC2H}



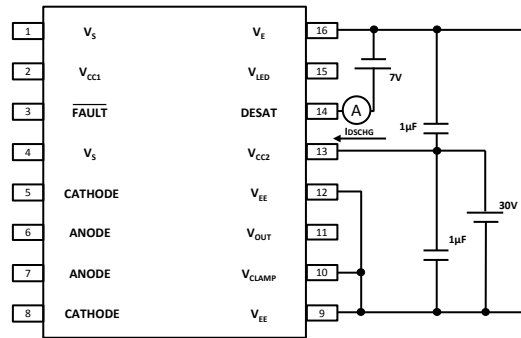
Test Circuit 6: I_{CC2L}



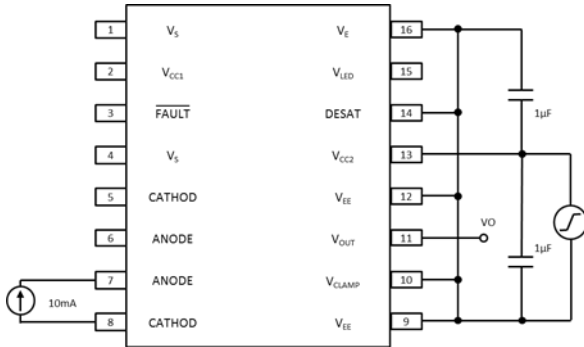
Test Circuit 7: I_{CHG}



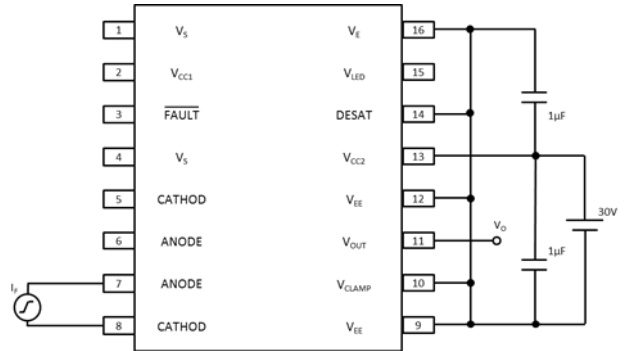
Test Circuit 8: I_DSCHG



Test Circuit 9: V_{UVLO}

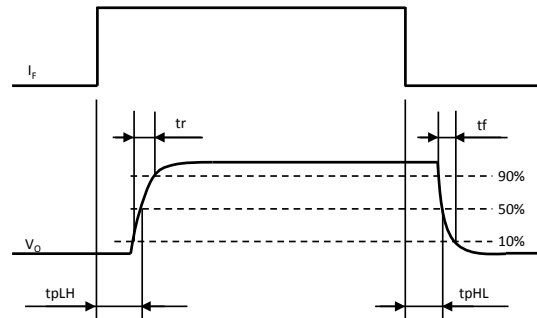
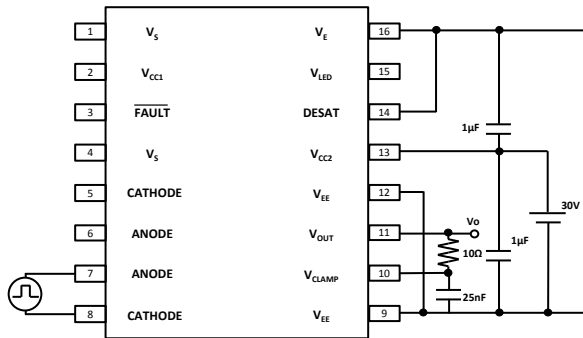


Test Circuit 10: I_{FLH}



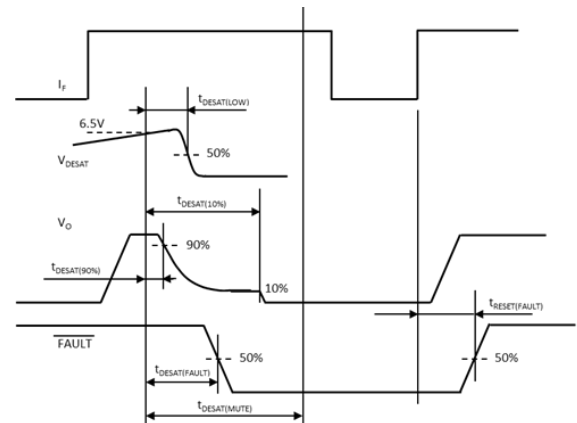
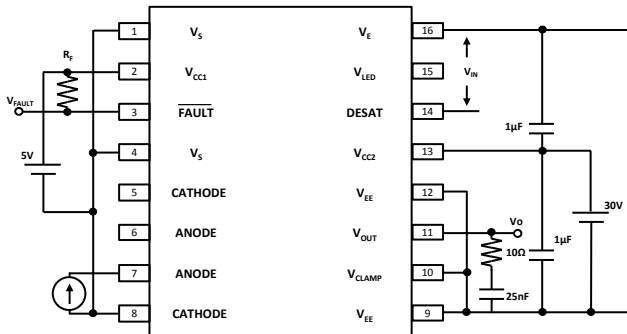
Test Circuit 11: t_{pLH}, t_{pHL}, t_r, t_f, | t_{pHL}-t_{pLH} |

I_F = 10 mA (P.G.)
 (f = 10kHz, duty = 50%, t_r = t_f = 5ns of less)

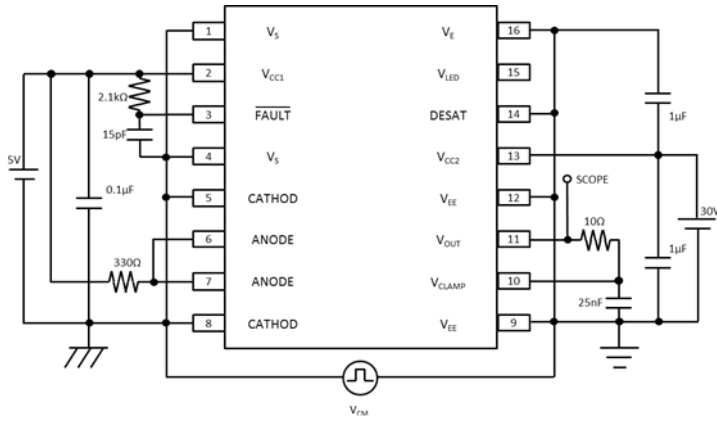


Test Circuit 12: t_{DESAT(90%)}, t_{DESAT(10%)}, t_{DESAT(FAULT)}, t_{DESAT(Low)}, t_{DESAT(MUTE)}, t_{RESET(FAULT)}

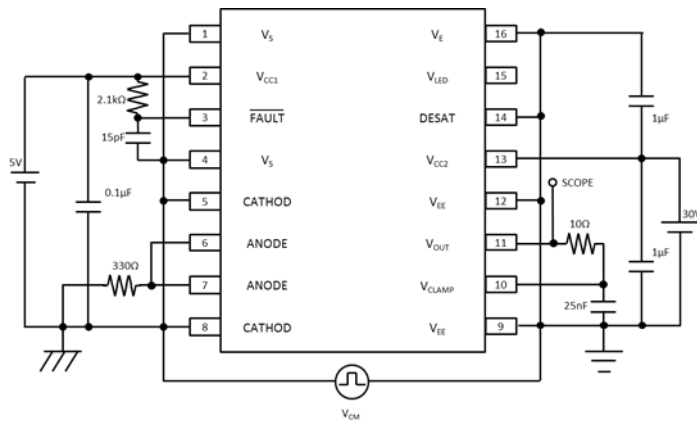
I_F = 10 mA (P.G.)
 (f = 10kHz, duty = 50%, t_r = t_f = 5ns of less)



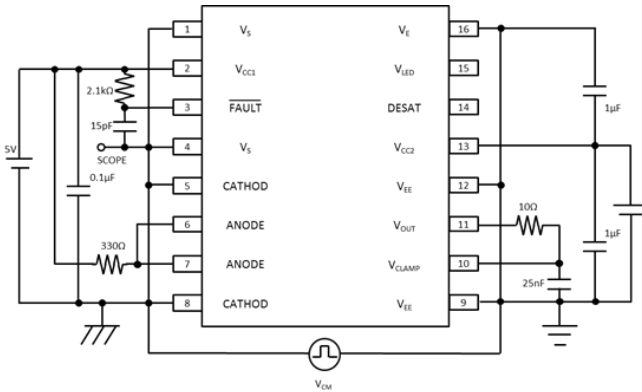
Test Circuit 13: CMR_LED1 ON



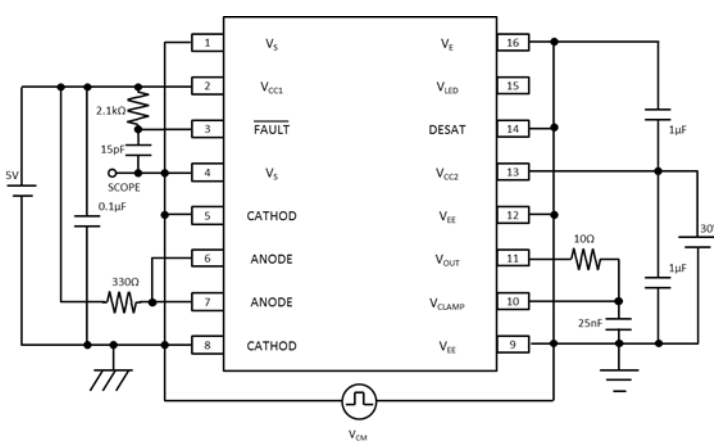
Test Circuit 13: CMR_LED1 OFF



Test Circuit 13: CMR_LED2 ON

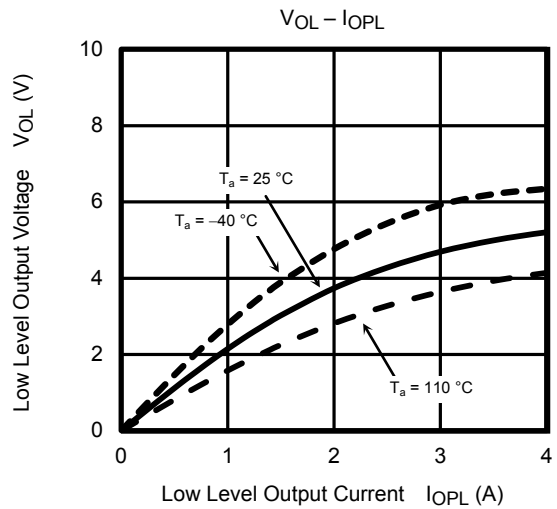
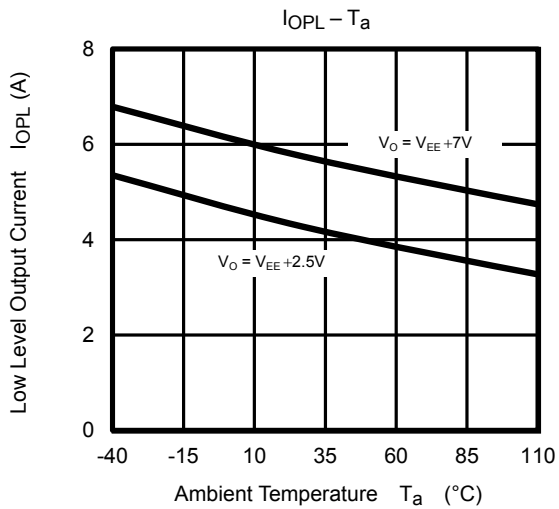
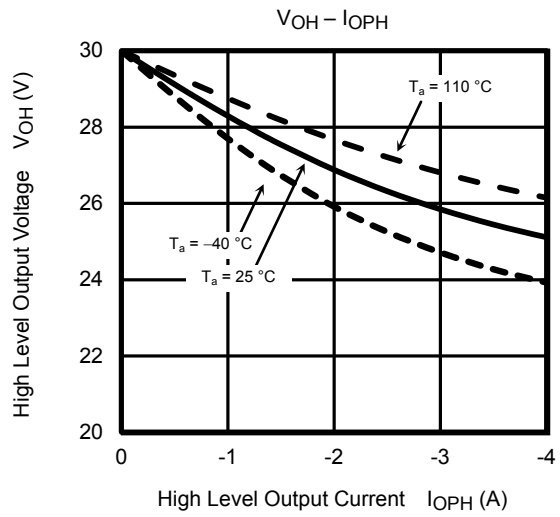
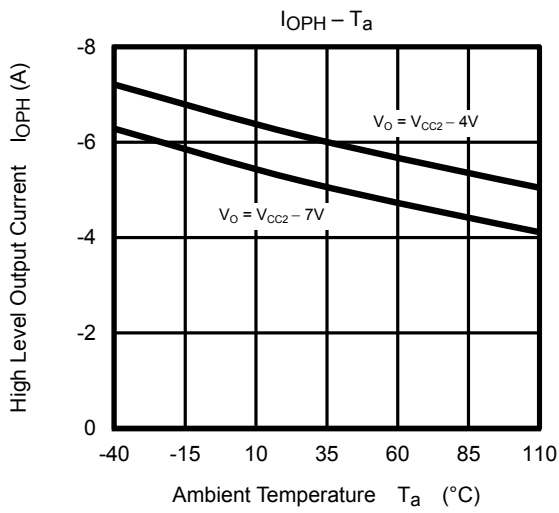
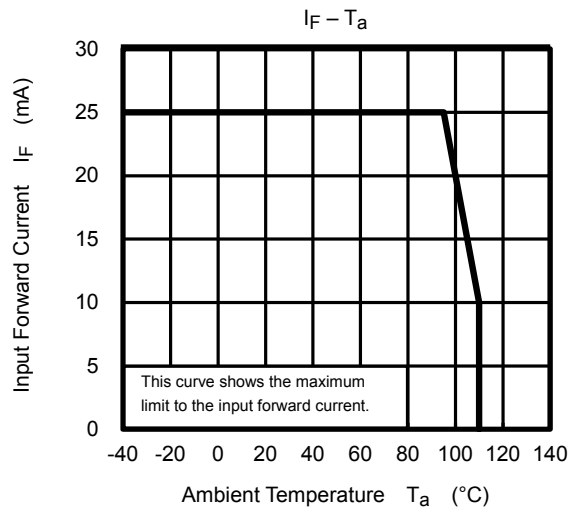
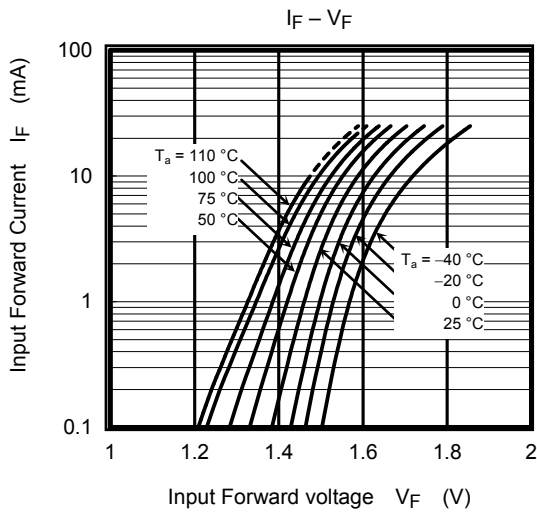


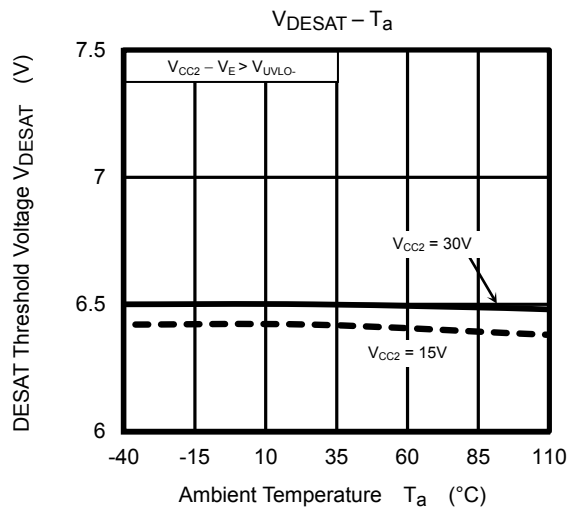
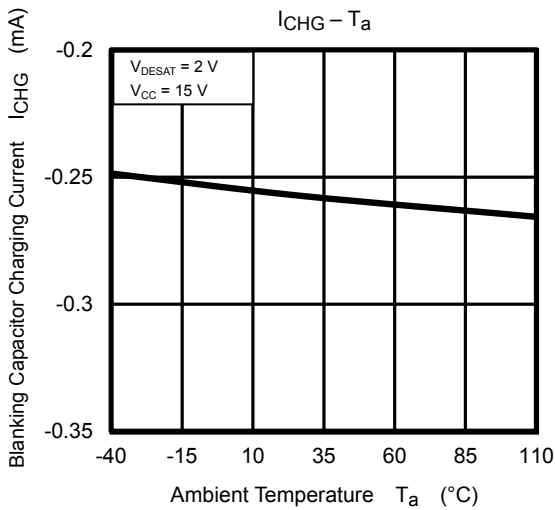
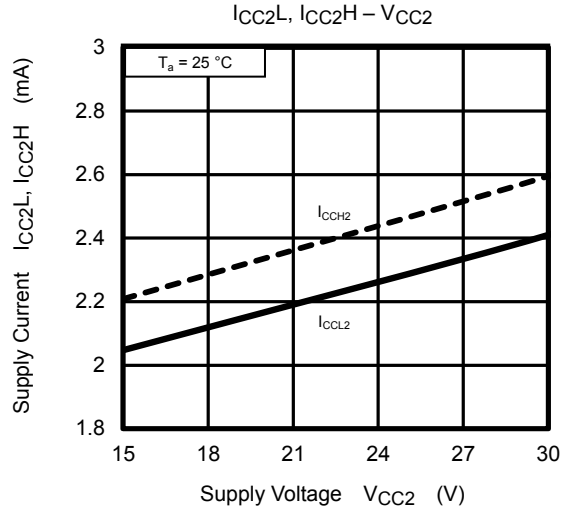
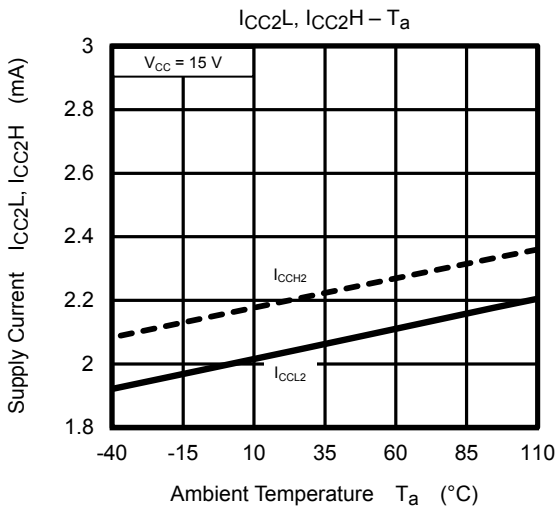
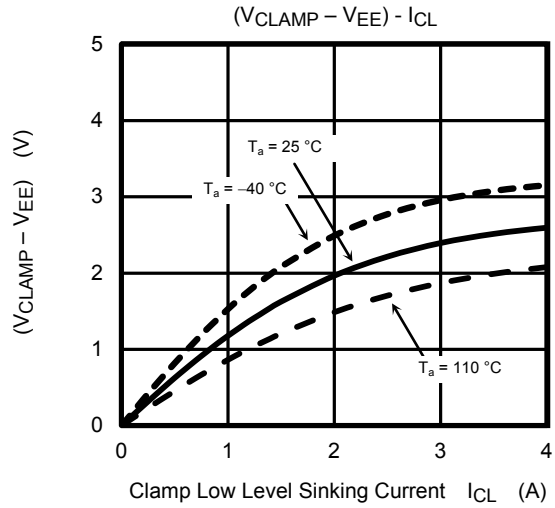
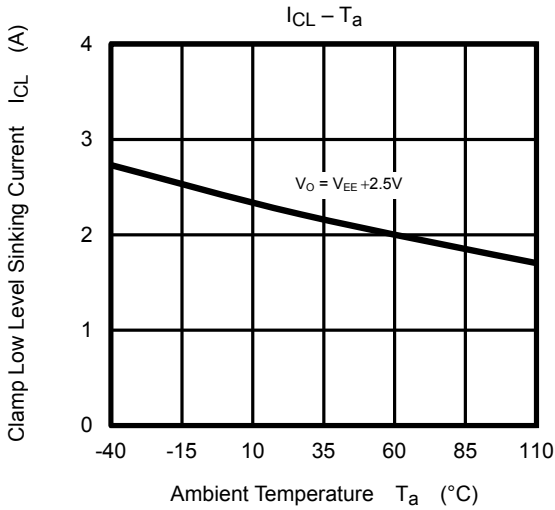
Test Circuit 13: CMR_LED2 OFF

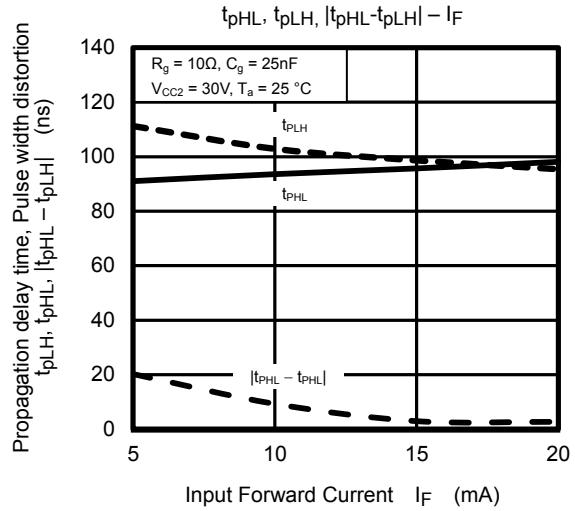
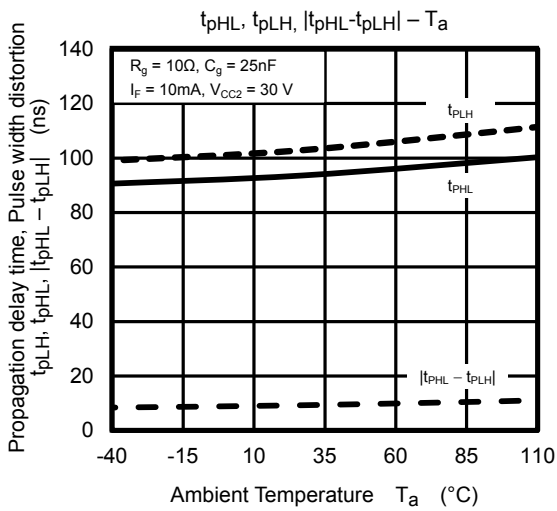
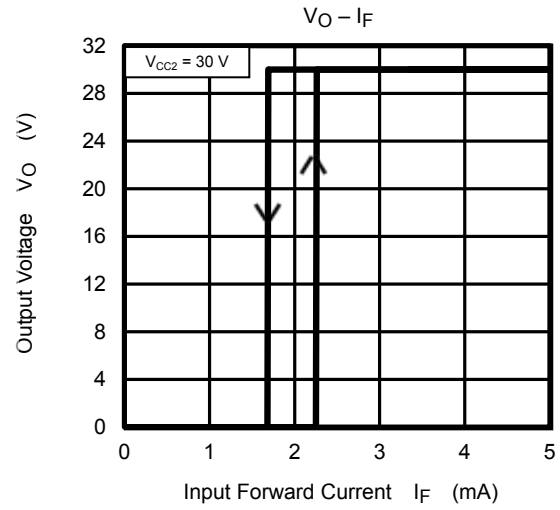
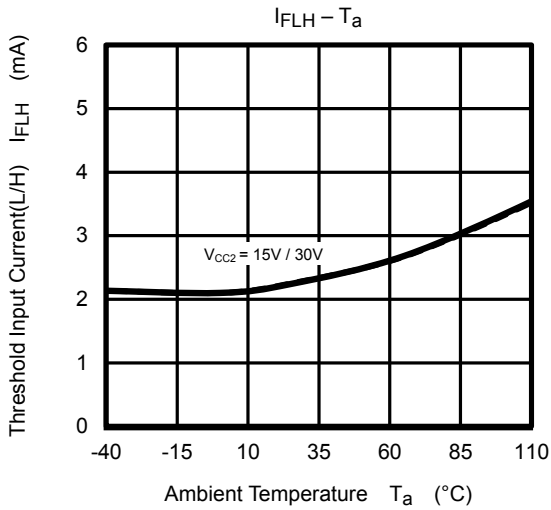
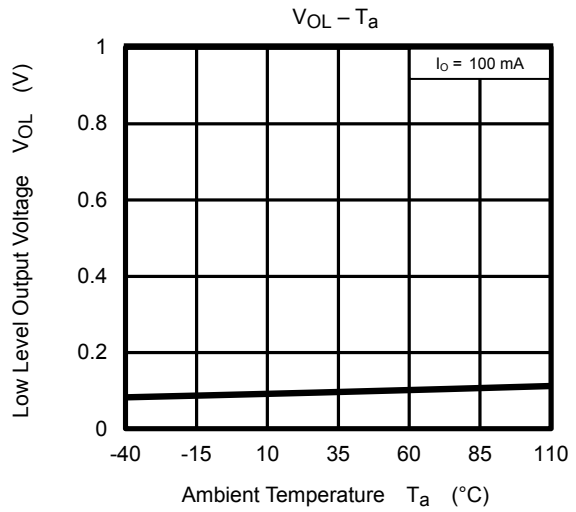
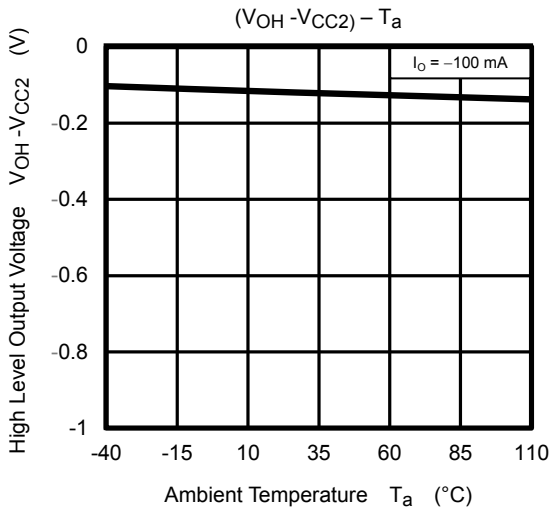


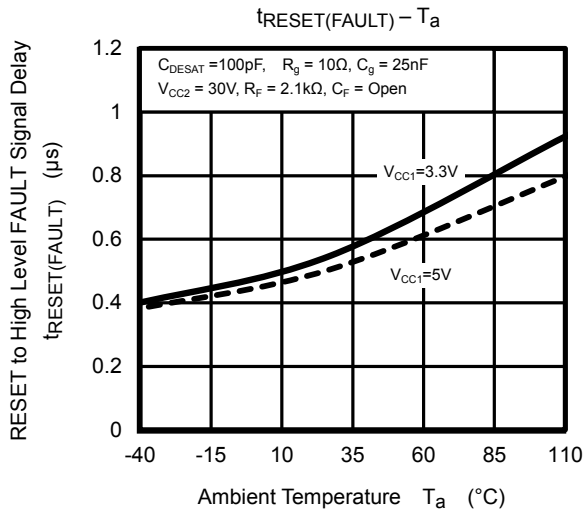
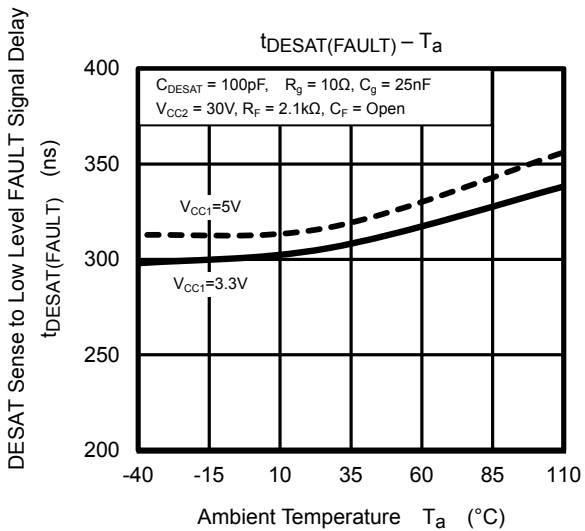
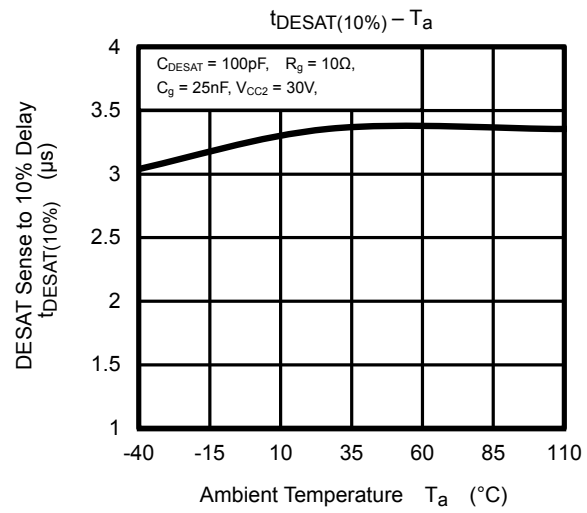
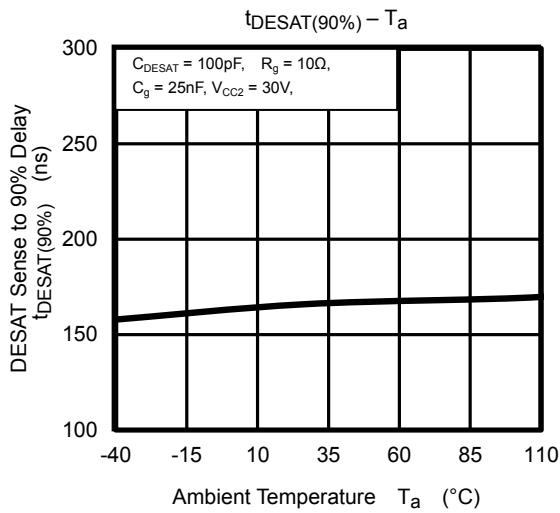
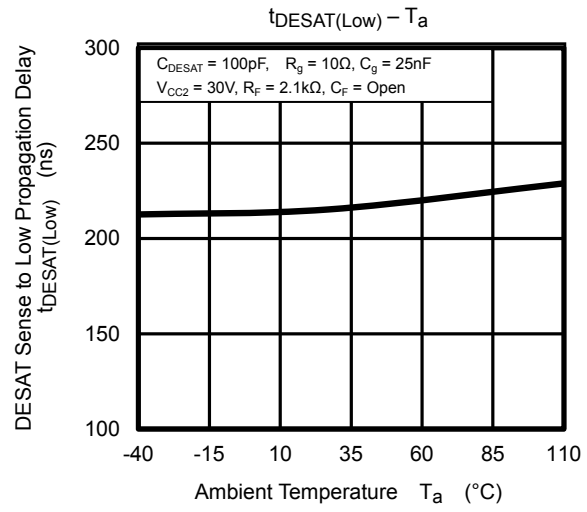
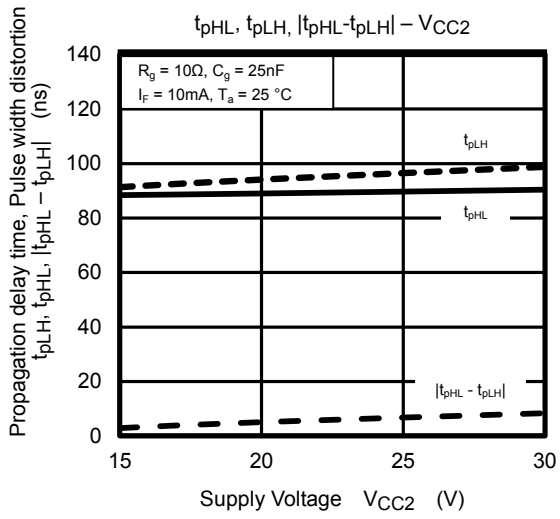
CM_L (CM_H) is the maximum rate of rise (fall) of the common mode voltage that can be sustained with the output voltage in the LOW (HIGH) state.

Characteristics Curve









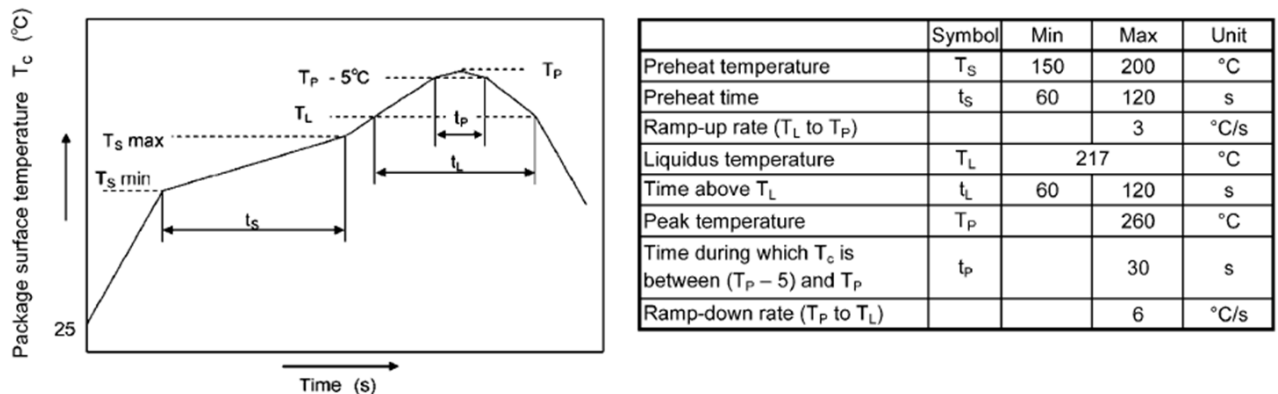
PRECAUTIONS OF SURFACE MOUNTING TYPE PHOTOCOUPLER SOLDERING & GENERAL STORAGE

(1) Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, Irrespective of whether a soldering iron or a reflow soldering method is used.

1) When Using Soldering Reflow

- Reflow soldering must be performed once or twice.
- The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

2) When using soldering Flow

- Apply preheating of 150 °C for 60 to 120 seconds.
 - Mounting condition of 260 °C and less within 10 seconds is recommended.
 - Flow soldering must be performed once

3) When using soldering Iron

- Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C.
- Heating by soldering iron must be only once per 1 lead

(2) Precautions for General Storage

- 1) Do not store devices at any place where they will be exposed to moisture or direct sunlight.
- 2) When transportation or storage of devices, follow the cautions indicated on the carton box.
- 3) The storage area temperature should be kept within a temperature range of 5 °C to 35 °C, and relative humidity should be maintained at between 45% and 75%.
- 4) Do not store devices in the presence of harmful (especially corrosive) gases, or in dusty conditions.
- 5) Use storage areas where there is minimal temperature fluctuation. Because rapid temperature changes can cause condensation to occur on stored devices, resulting in lead oxidation or corrosion, as a result, the solderability of the leads will be degraded.
- 6) When repacking devices, use anti-static containers.
- 7) Do not apply any external force or load directly to devices while they are in storage.
- 8) If devices have been stored for more than two years, even though the above conditions have been followed, it is recommended that solderability of them should be tested before they are used.

Specifications for Embossed-Tape Packing (TP) for SO16L Coupler

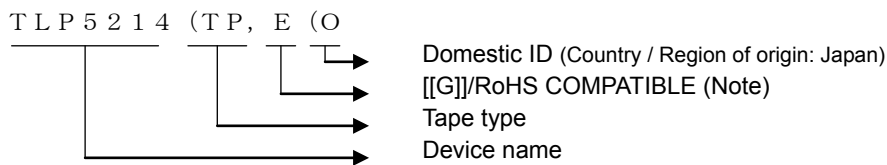
1. Applicable Package

Package	Product Type
SO16L	Long creepage Coupler

2. Product Naming System

Type of package used for shipment is denoted by a symbol suffix after a product number. The method of classification is as below.

(Example)



3. Tape Dimensions

3.1 Orientation of Device in Relation to Direction of Tape Movement

Device orientation in the recesses is as shown in Figure 1.

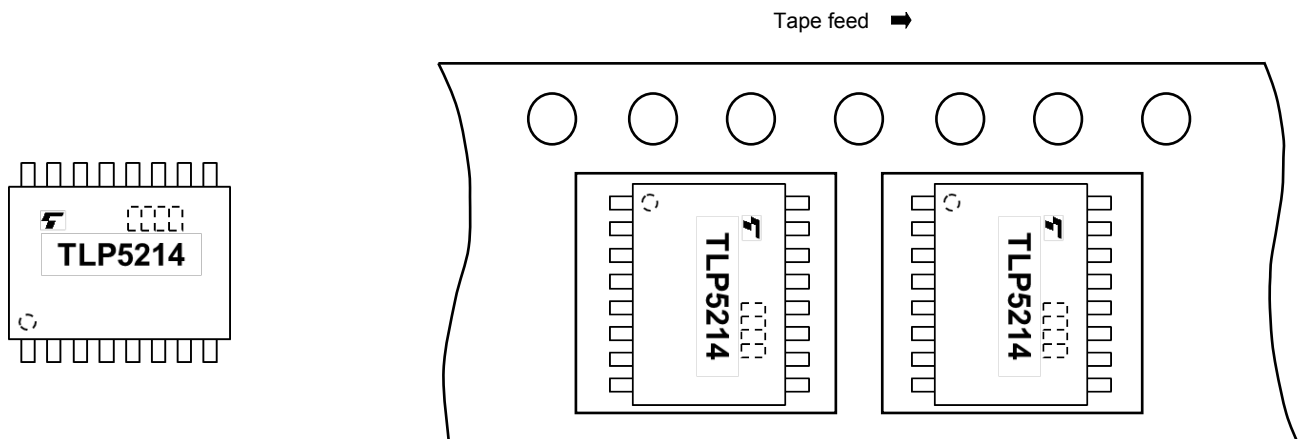


Figure 1 Device Orientation

3.2 Packing Quantity : 1500 per reel

3.3 Empty Device Recesses Are as Shown in Table 1.

Table1 Empty Device Recesses

	Standard	Remarks
Occurrences of 2 or more successive empty device recesses	0	Within any given 40-mm section of tape, not including leader and trailer
Single empty device recesses	6 device (max) per reel	Not including leader and trailer

3.4 Start and End of Tape

The start of the tape has 14 or more empty holes. The end of the tape has 34 or more empty holes and more than 30mm only for a cover tape.

3.5 Tape Specification

- (1) Material: Plastic (production against electrostatics)
- (2) Dimensions: The tape dimensions are shown in Figure 2 and Table 2.

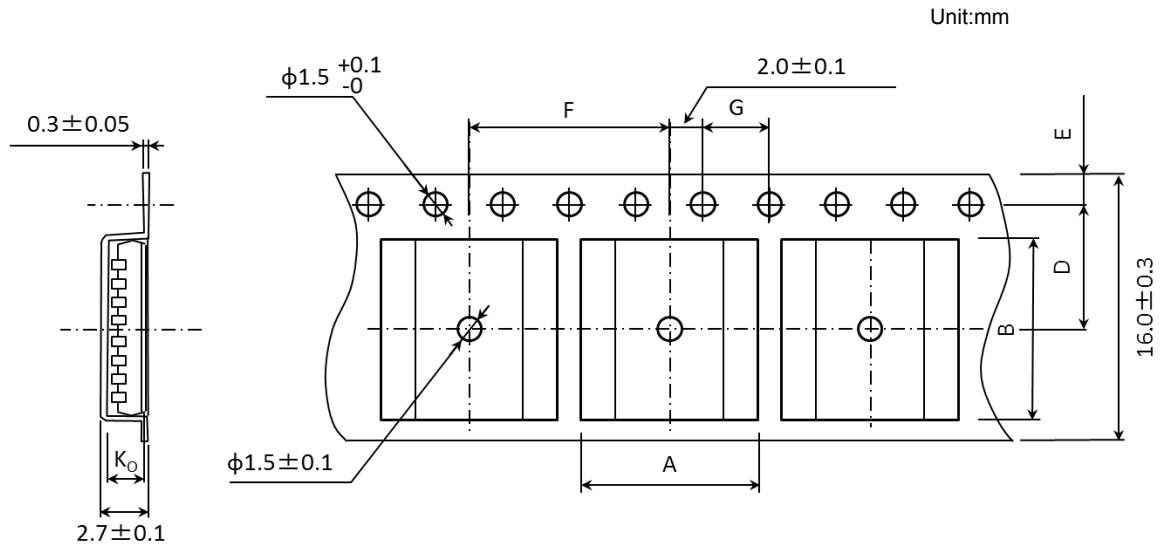


Figure 2 Tape Forms

Table 2 Tape Dimensions

Unit: mm
Unless otherwise specified: ± 0.1

Symbol	Dimension	Remark
A	10.4	—
B	10.7	—
D	7.5	Center line of indented square hole and sprocket hole
E	1.75	Distance between tape edge and hole center
F	12.0	Cumulative error $\begin{matrix} +0.1 \\ -0.3 \end{matrix}$ per 10 feed holes
G	4.0	Cumulative error $\begin{matrix} +0.1 \\ -0.3 \end{matrix}$ per 10 feed holes
K_0	2.4	Internal space

3.6 Reel

- (1) Material: Plastic
- (2) Dimensions: The reel dimensions are as shown in Figure 3 and Table 3.

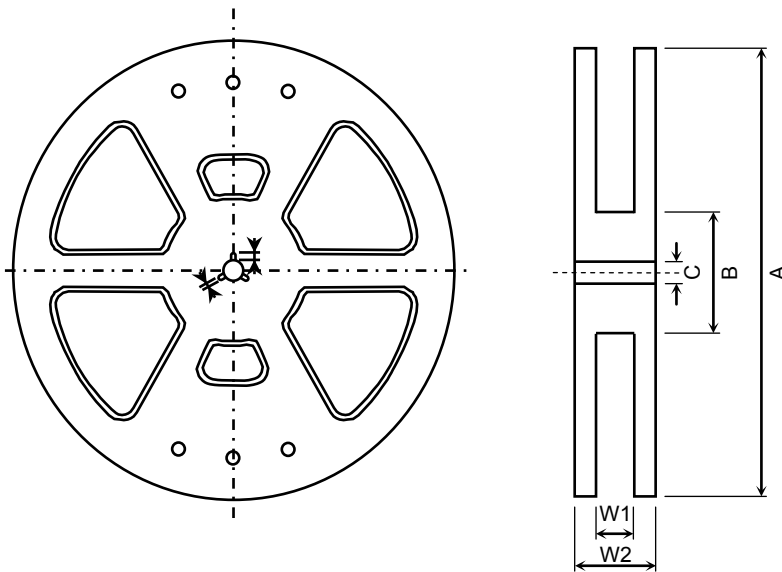


Table 3 Reel Dimension

Unit: mm

Symbol	Dimension
A	$\Phi 330 \pm 2$
B	$\Phi 100 \pm 1$
C	$\Phi 13 \pm 0.5$
E	2.0 ± 0.5
U	4.0 ± 0.5
W1	17.4 ± 1.0
W2	21.4 ± 1.0

Figure 3 Reel Forms

4. Packing

Either one reel or ten reels of photocoupler are packed in a shipping carton.

5. Label Indication

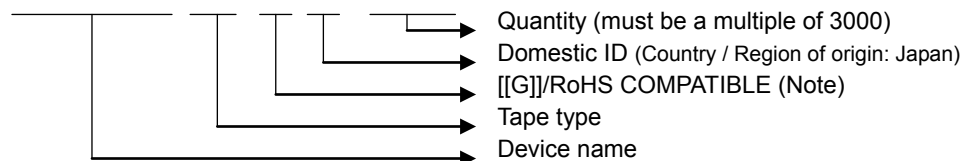
The carton bears a label indicating the product number, the symbol representing classification of standard, the quantity, the lot number and Toshiba company name.

6. Ordering Method

When placing an order, please specify the product number, the CTR rank, the tape and the quantity as shown in the following example.

(Example)

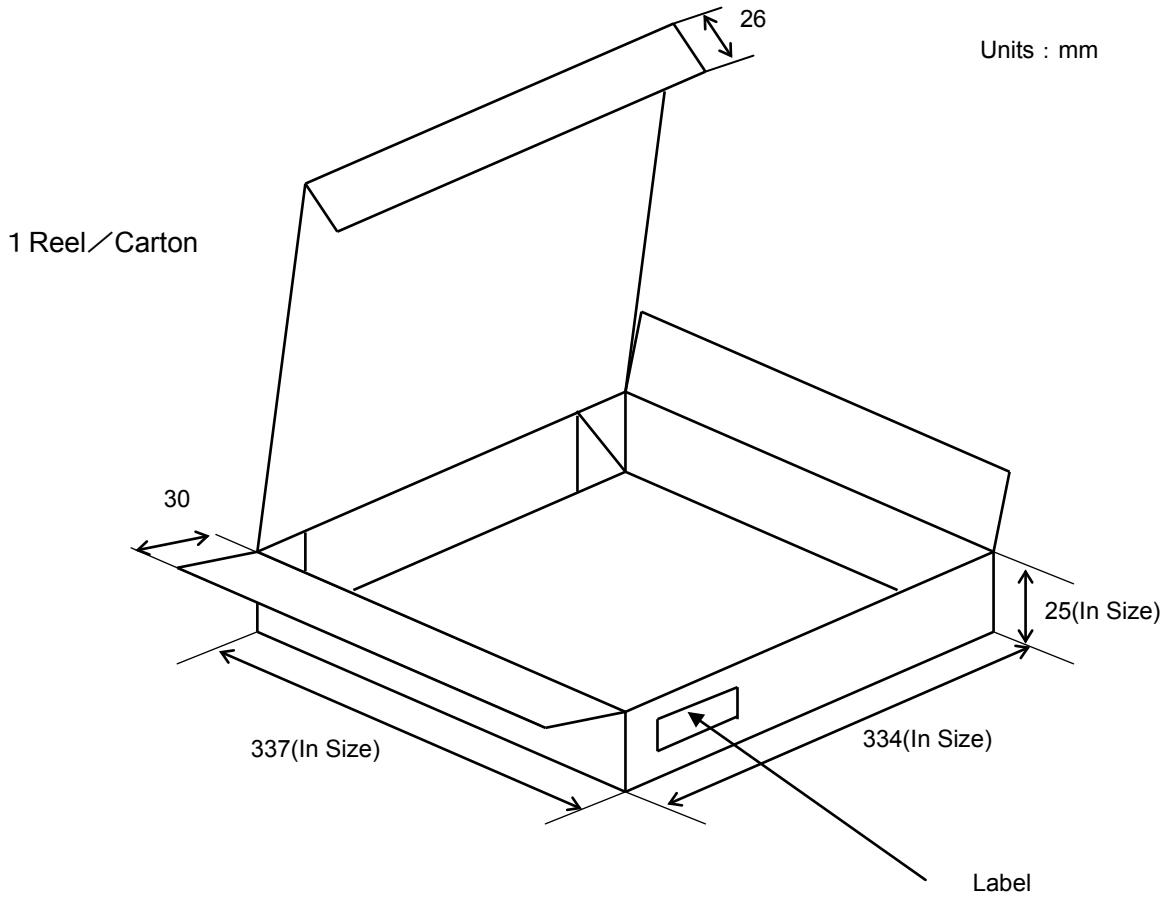
TLP5214 (TP, E (O) 1500Pcs.



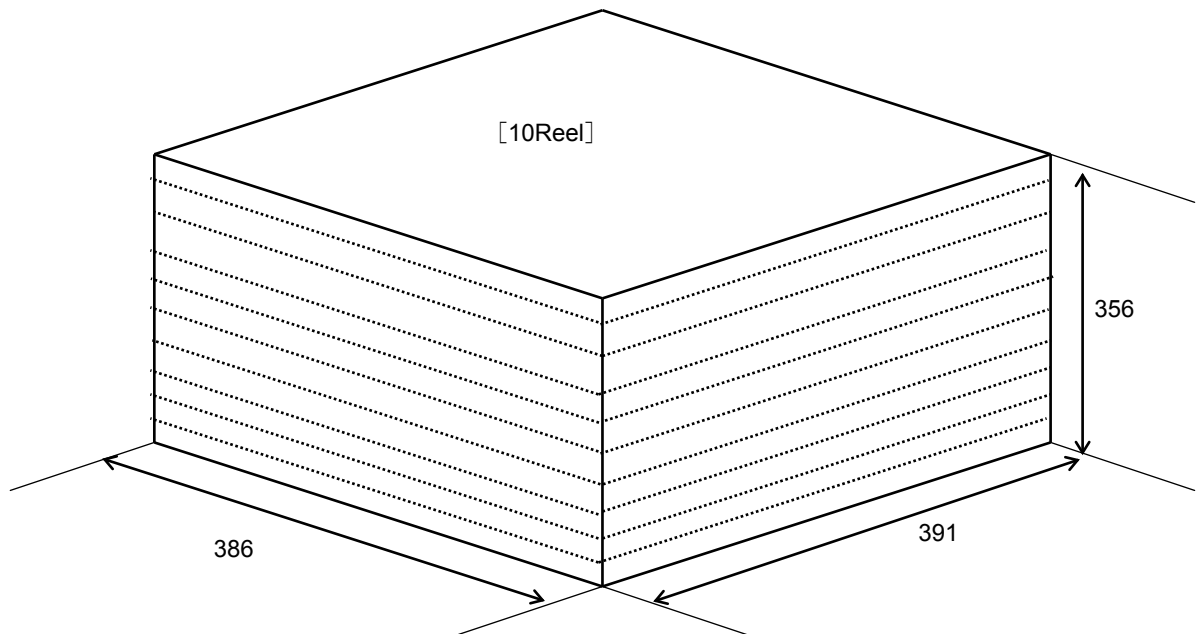
Note : Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

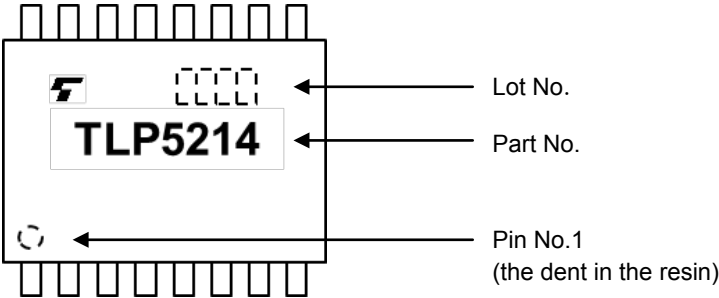
7. MethodPacking Dimensions (φ 330mm)



10Reel / Carton



8. Marking



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